

02/22/02  
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02/25/02  
Docket No.: M-12589 US

February 22, 2002

J1017 U.S. PTO  
02/22/02  
J10/080468

BOX PATENT APPLICATION  
Commissioner for Patents  
Washington, D.C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventor: Hua Ji  
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench

X Return Receipt Postcard  
X This Transmittal Letter (in duplicate)  
12 page(s) Specification (not including claims)  
4 page(s) Claims  
1 page Abstract  
6 Sheet(s) of Drawings  
2 page(s) Declaration For Patent Application and Power of Attorney  
1 page(s) Recordation Form Cover Sheet (in duplicate)  
1 page(s) Assignment

<u>CLAIMS AS FILED</u>							
For	Number Filed	Number Extra		Rate		\$	Basic Fee
Total Claims	29	-20	=	9	x \$18.00	=	\$ 740.00
Independent Claims	2	-3	=	0	x \$84.00	=	\$ 0.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application						\$	
<input type="checkbox"/> Fee for Request for Extension of Time						\$	

Please make the following charges to Deposit Account 19-2386:

- Total fee for filing the patent application in the amount of \$ 902.00  
 The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:

EV 022456809 US

Respectfully submitted,

  
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